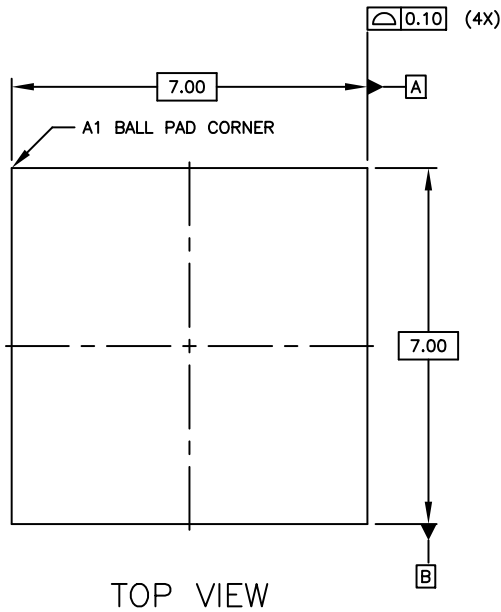


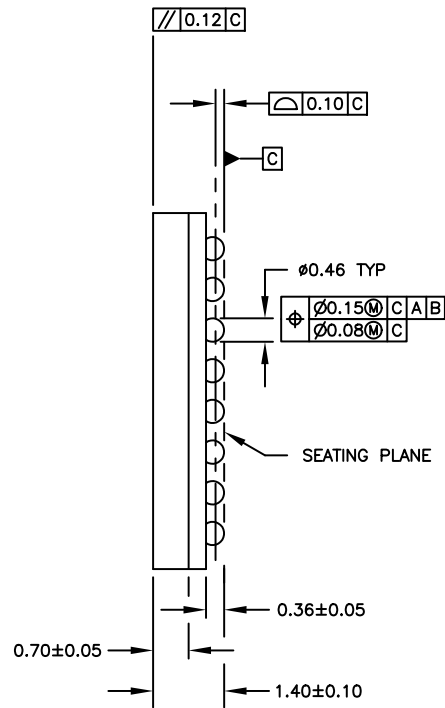
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

**LFBGA 64, 7x7**  
**CASE 566AF-01**  
**ISSUE O**

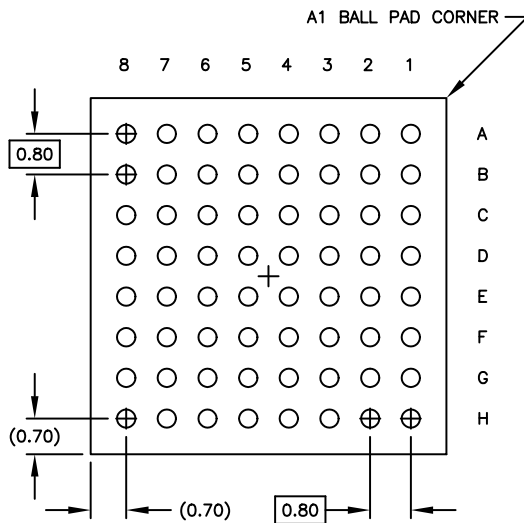
DATE 31 JUL 2008



TOP VIEW



SIDE VIEW



BOTTOM VIEW

64 SOLDER BALLS

W/B No.	BALL No.	W/B No.	BALL No.	W/B No.	BALL No.	W/B No.	BALL No.
1	B1	17	H2	33	G8	49	A7
2	D4	18	E4	34	E5	50	D5
3	C1	19	H3	35	F8	51	A6
4	D3	20	F4	36	E6	52	C5
5	C2	21	G3	37	F7	53	B6
6	D1	22	H4	38	E8	54	A5
7	E3	23	F5	39	D6	55	C4
8	D2	24	G4	40	E7	56	B5
9	E1	25	H5	41	D8	57	A4
10	E2	26	G5	42	D7	58	B4
11	F1	27	H6	43	C8	59	A3
12	F3	28	F6	44	C6	60	C3
13	F2	29	G6	45	C7	61	B3
14	G1	30	H7	46	B8	62	A2
15	G2	31	G7	47	B7	63	B2
16	H1	32	H8	48	A8	64	A1

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<b>REFERENCE:</b>		
<b>DESCRIPTION:</b>	<b>LFBGA 64, 7X7</b>	<b>PAGE 1 OF 2</b>

